

**REMARKS**

**Status of the Application**

Claims 1, 3-7, 27, 28 and 30 are all the claims pending in the application. Claims 1, 3-6 and 27 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Takayama et al. (US 2003/0089913A1) in view of Burroughes et al. (US 6592969 B1). Claims 7, 28 and 30 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Takayama et al. and Burroughes et al. in view of Ishida (US 4,661,428).

By this Amendment, Applicant is amending claim 1, and canceling claims 3-5, 7 27, 28 and 30.

**Claim Rejections -- 35 U.S.C. § 103(a)**

The Examiner alleges that a combination of the flexible electronic device in Takayama, the substrate taught in Burroughs, and the thermal conductivity taught in Ishida teaches or suggests all of elements of amended claim 1. Applicant respectfully disagrees. The Examiner concedes that Takayama (U.S. 2003/0089913) fails to teach or suggest that such a thin glass substrate not larger than 200  $\mu\text{m}$  can be used in such a way that an electrically active layer of the electrically active thin film transistor is disposed directly on the glass substrate. However, the Examiner alleges that Burroughes (U.S. 6,592,969) cures the deficiencies noted in Takayama. However, there is no motivation to replace the substrate insulating film 202 in Takayama by the glass layer 4 in Burroughes. This is because Burroughes teaches away from forming the thin film transistor. Specifically, Burroughes fails to provide a specific teaching as to why one of

ordinary skill in the art would be motivated to replace the substrate insulating film 202 in Takayama with the glass layer 4 taught in Burroughes.

Further, the Examiner concedes that Takayama and Burroughes fail to disclose either a thin film transistor or a flexible film having a thermal conductivity higher than 0.01 W/cm• deg. The Examiner alleges that Ishida (US4661428) teaches or suggests this element of amended claim 1. However, Ishida fails to disclose either a thin film transistor or the glass substrate. Ishida merely teaches to use the electrically conductive substrate 11 for forming the photosensitive element including the first photoconductive layer 12 thereon. The substrate 11 in Ishida must be electrically conductive, therefore, Ishida provides no motivation to make the *plastic* substrate 201 in Takayama to have the thermal conductivity higher than 0.01 W/cm deg. Rather, Ishida teaches that a plastic substrate must be covered in copper to function as intended in Ishida. See col. 4, lines 56-59. Because there is no motivation to combine the references as alleged by the Examiner, amended claim 1 is patentable over the applied art. Claim 6 is patentable at least by virtue of its dependency from claim 1.

### **Conclusion**

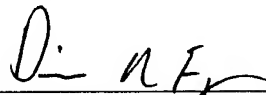
In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

AMENDMENT UNDER 37 CFR § 1.114(c)  
U.S. Application No. 10/751,631

Q79065

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Dion R. Ferguson  
Registration No. 59,561

SUGHRUE MION, PLLC  
Telephone: (202) 293-7060  
Facsimile: (202) 293-7860

WASHINGTON OFFICE

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